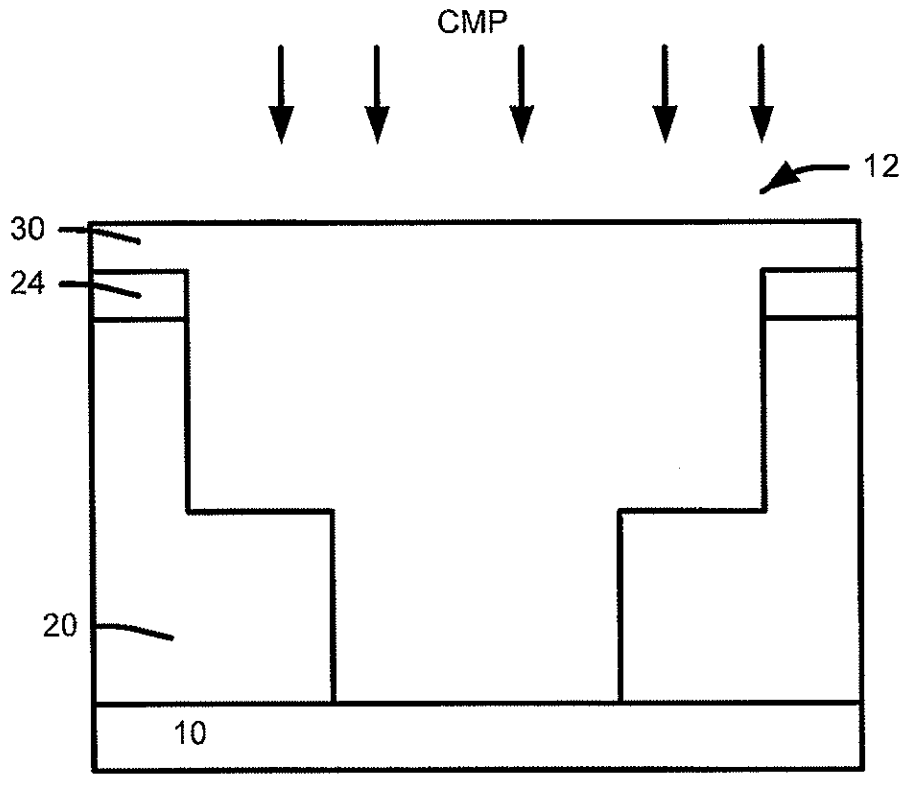


FIGURE 1

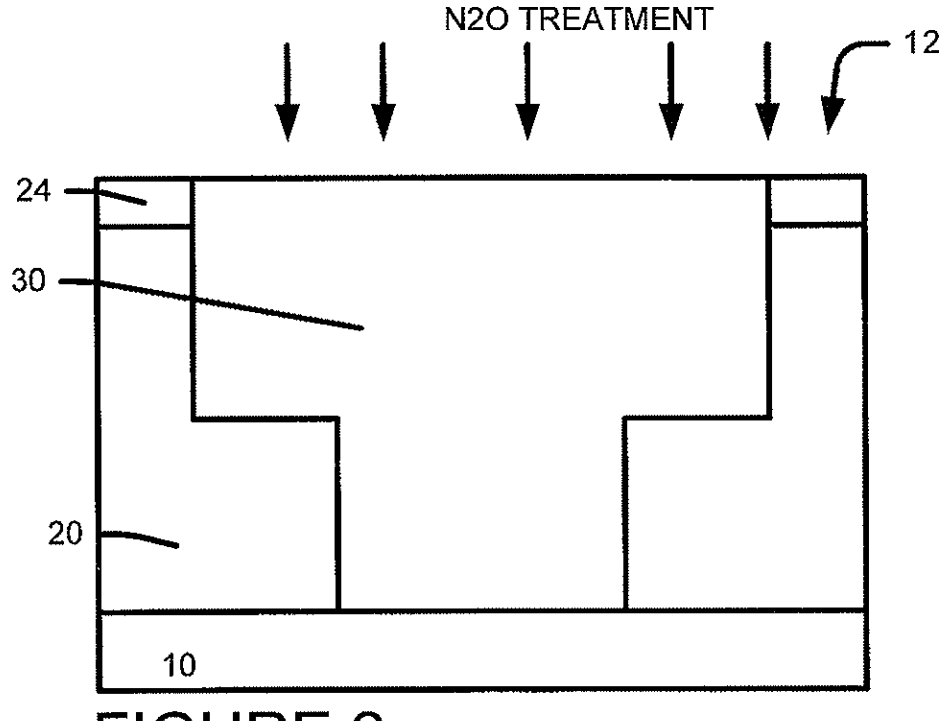


FIGURE 2

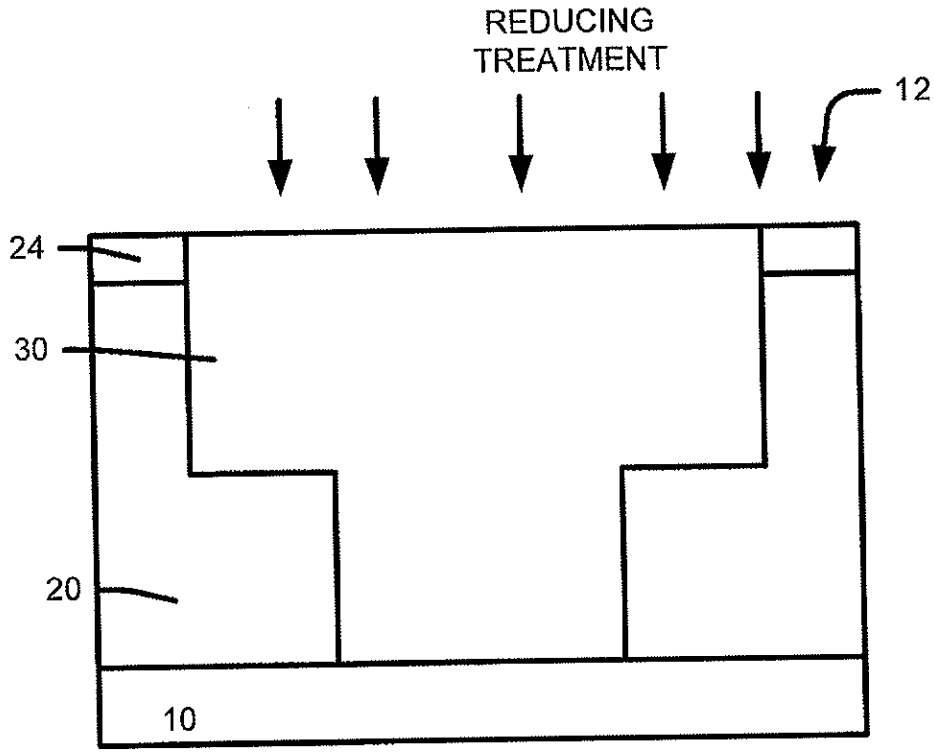


FIGURE 3

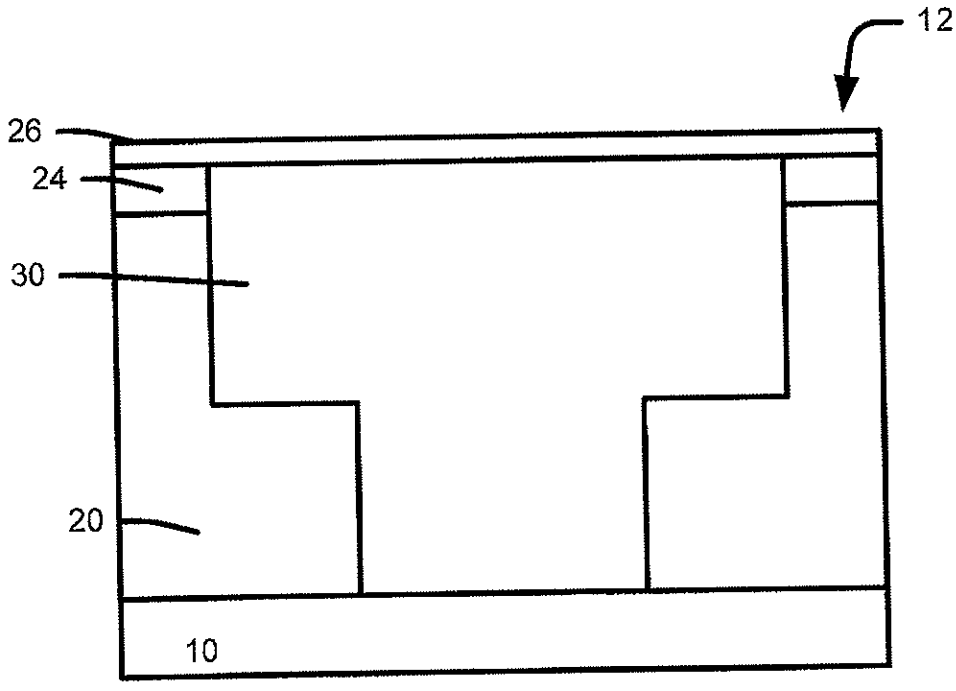
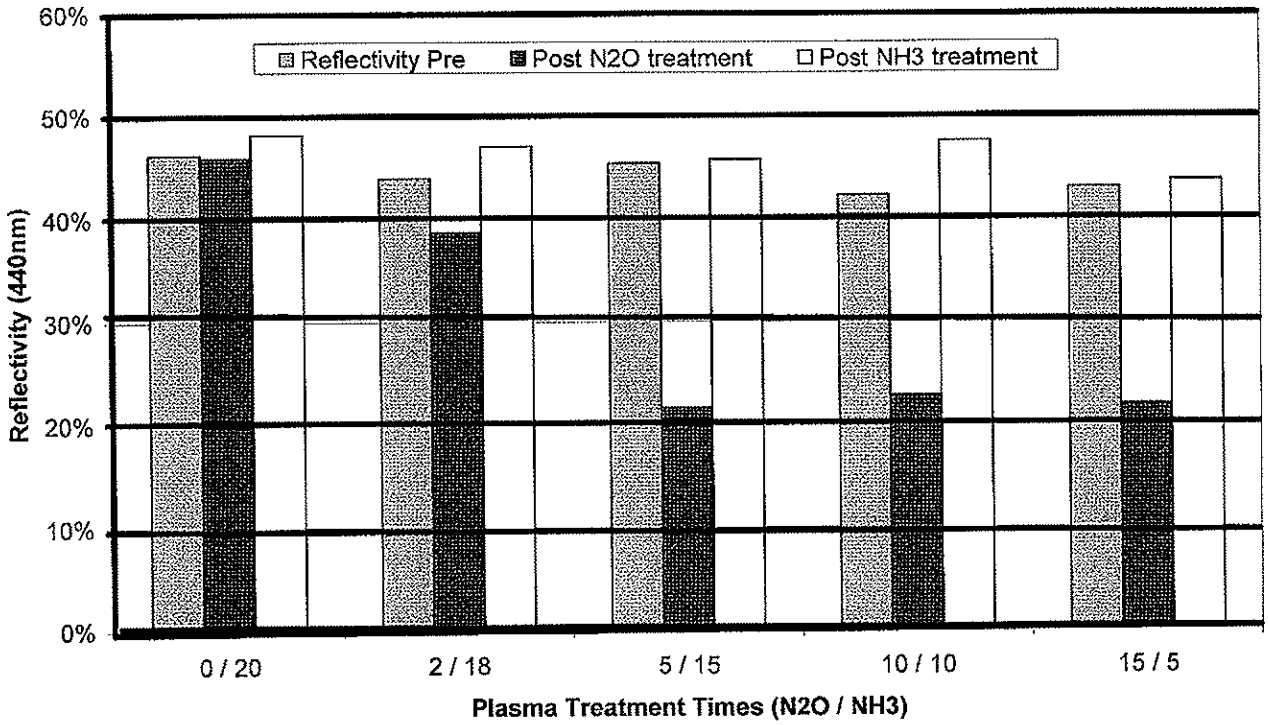


FIGURE 4



LEGEND
1) Incoming substrate reflectivity was 42-46%
2) N2O plasma treatment reaches saturation point within 5 seconds at ~21%
3) NH3 plasma treatment recovery of saturated CuO wafers takes <10 seconds
note: Based on the reflectivity, the CuO thickness can be calibrated.

FIGURE 5